

ESD Protection Diodes Silicon Epitaxial Planar

DF2S23P2FU

General

The DF2S23P2FU is a TVS diode (ESD protection diode) protects semiconductor devices used in mobile device interfaces and other applications to protect against static electricity and noise.

The DF2S23P2FU has realized high I_{PP}, in order to protect a semiconductor devices from the indirect lightning stroke and the transition voltage (at the time of power activation).

Furthermore, the DF2S23P2FU is housed in an standard package ($2.5 \text{ mm} \times 1.25 \text{ mm}$), it can be used for various applications.

2. Applications

Mobile Equipment

- · Smartphones
- · Tablets
- · Notebook PCs

Desktop PCs

Note: This product is designed for protection against electrostatic discharge (ESD) and is not intended for any other purpose, including, but not limited to, voltage regulation.

3. Features

- (1) Suitable for use with a 20 V signal line. $(V_{RWM} \le 21 \text{ V})$
- (2) Protects devices with its high ESD performance.

$$(V_{ESD} = \pm 30 \text{ kV (Contact / Air)} @IEC61000-4-2)$$

(3) Low dynamic resistance protects semiconductor devices from static electricity and noise.

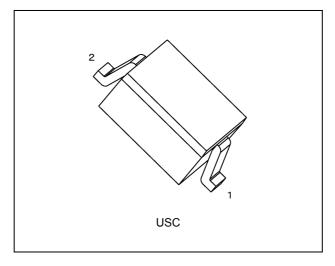
 $(R_{DYN} = 0.13 \Omega \text{ (typ.)})$

(4) Low clamping voltage characteristic protects semiconductor devices from static electricity and noise. $(V_C = 30 \text{ V}@I_{PP} = 14 \text{ A (typ.)})$

(VC = 50 V@1PP = 14 A (typ.//

(5) Compact package is suitable for use in high density board layouts such as in mobile devices. $(2.5 \text{ mm} \times 1.25 \text{ mm} \text{ size (Nickname: USC)})$

4. Packaging



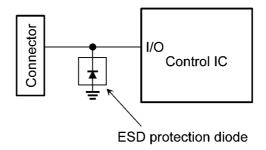
Start of commercial production

2018-08

2018-08-07



5. Example of Circuit Diagram

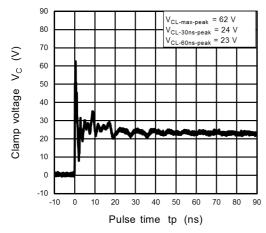


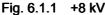
6. Quick Reference Data

Characteristics	Symbol	Note Test Condition		Min	Тур.	Max	Unit
Working peak reverse voltage	V_{RWM}	(Note 1)			_	21	٧
Dynamic resistance	R _{DYN}	(Note 2)	_	_	0.13	_	Ω
Electrostatic discharge voltage (IEC61000-4-2) (Contact)	V _{ESD}	(Note 3)	-	_	_	30	kV

- Note 1: Recommended operating condition.
- Note 2: TLP parameters: $Z0 = 50 \Omega$, tp = 100 ns, tr = 300 ps, averaging window: t1 = 30 ns to t2 = 60 ns, extraction of dynamic resistance using least squares fit of TLP characteristics between $I_{PP1} = 16$ A and $I_{PP2} = 30$ A.
- Note 3: Criterion: No damage to devices.

6.1. ESD Clamp Waveform (Note)





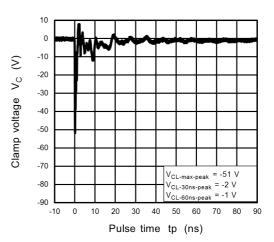


Fig. 6.1.2 -8 kV

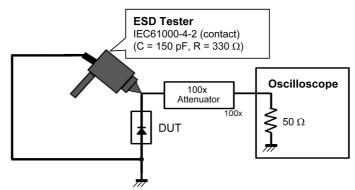
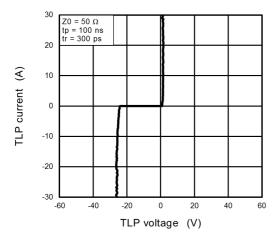


Fig. 6.1.3 IEC61000-4-2 (Contact)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

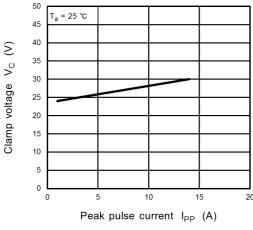


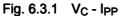
6.2. TLP Characteristics (Note)



Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

6.3. Clamp Voltage - Peak Pulse Current (V_C - I_{PP}) (Note)





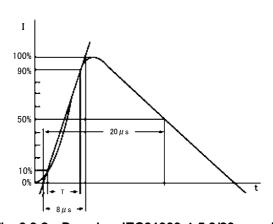


Fig. 6.3.2 Based on IEC61000-4-5 8/20 μs pulse.

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



7. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

Characteristics	Symbol	Note	Rating	Unit
Electrostatic discharge voltage (IEC61000-4-2) (Contact)	V _{ESD}	(Note 1)	±30	kV
Electrostatic discharge voltage (IEC61000-4-2) (Air)			±30	
Peak pulse power (tp = 8/20 μs)	P _{PK}		500	W
Peak pulse current (tp = 8/20 μs)	I _{PP}	(Note 2)	14	Α
Junction temperature	Tj		150	°C
Storage temperature	T _{stg}		-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: According to IEC61000-4-2.

Note 2: According to IEC61000-4-5.

8. Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

V_{RWM}: Working peak reverse voltage V_{BR}: Reverse breakdown voltage I_{BR}: Reverse breakdown current

I_R: Reverse current V_C: Clamp voltage I_{PP}: Peak pulse current R_{DYN}: Dynamic resistance

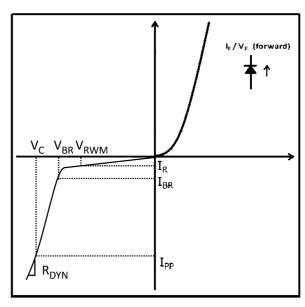


Fig. 8.1 Definitions of Electrical Characteristics

Characteristics	Symbol	Note	Test Condition	Min	Тур.	Max	Unit
Working peak reverse voltage	V_{RWM}	(Note 1)	_	_	_	21	V
Total capacitance	Ct		V _R = 0 V, f = 1 MHz	_	160	_	pF
Dynamic resistance	R _{DYN}	(Note 2)	_	_	0.13	_	Ω
Reverse breakdown voltage	V_{BR}		I _{BR} = 1 mA	21.5	24.1	25.5	V
Reverse current	I _R		V _{RWM} = 21 V	_	_	0.1	μА
Clamp voltage	V _C	(Note 3)	I _{PP} = 1 A	_	24.2	_	V
			I _{PP} = 14 A	_	30	35.7	
		(Note 2)	I _{TLP} = 16 A	_	25.5	_	V
			I _{TLP} = 30 A	_	27.3	_	

Note 1: Recommended operating condition.

Note 2: TLP parameters: $Z0 = 50 \Omega$, tp = 100 ns, tr = 300 ps, averaging window: t1 = 30 ns to t2 = 60 ns, extraction of dynamic resistance using least squares fit of TLP characteristics between $I_{PP1} = 16$ A and $I_{PP2} = 30$ A.

Note 3: Based on IEC61000-4-5 $8/20 \mu s$ pulse.

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2018-08-07
Rev.2.0



9. Characteristics Curves (Note)

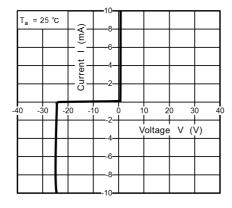


Fig. 9.1 I-V

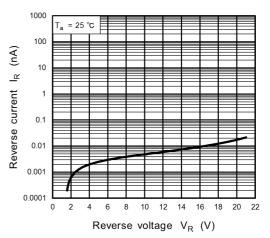
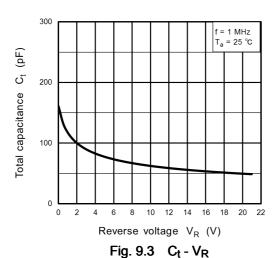


Fig. 9.2 I_R - V_R

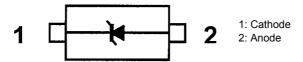


. .g. 0.0 0(1)

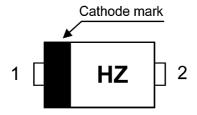
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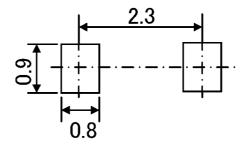
10. Internal Circuit



11. Marking (Top view)



12. Land Pattern Dimensions (for reference only)

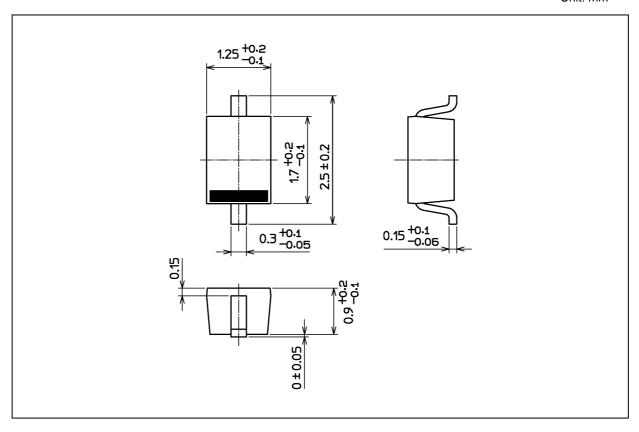


Unit: mm



Package Dimensions

Unit: mm



Weight: 4.5 mg (typ.)

	Package Name(s)	
Nickname: USC		



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